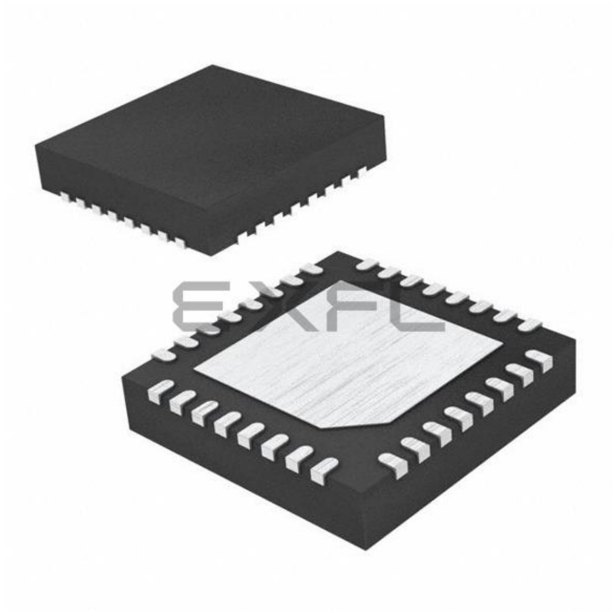
Microchip Technology - PIC24FJ128GB202T-I/MM Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SmartCard, SPI, UART/USART
Peripherals	AES, Brown-out Detect/Reset, DMA, I²S, HLVD, POR, PWM, WDT
Number of I/O	20
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN-S (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fj128gb202t-i-mm

TABLE 1-3: PIC24FJ128GB204 FAMILY PINOUT DESCRIPTION (CONTINUED)

Pin Function	Pin Number/Grid Locator			I/O	Input Buffer	Description
	28-Pin SPDIP/SOIC/ SSOP	28-Pin QFN-S	44-Pin TQFP/QFN			
RP0	4	1	21	I/O	ST	Remappable Peripheral (input or output).
RP1	5	2	22	I/O	ST	
RP2	6	3	23	I/O	ST	
RP3	7	4	24	I/O	ST	
RP5	2	27	19	I/O	ST	
RP6	3,15	28	20	I/O	ST	
RP7	16	13	43	I/O	ST	
RP8	17	14	44	I/O	ST	
RP9	18	15	1	I/O	ST	
RP10	21	18	8	I/O	ST	
RP11	22	19	9	I/O	ST	
RP13	24	21	11	I/O	ST	
RP14	25	22	14	I/O	ST	
RP15	26	23	15	I/O	ST	
RP16	—	—	25	I/O	ST	
RP17	—	—	26	I/O	ST	
RP18	—	—	27	I/O	ST	
RP19	—	—	36	I/O	ST	
RP20	—	—	37	I/O	ST	
RP21	—	—	38	I/O	ST	
RP22	—	—	2	I/O	ST	
RP23	—	—	3	I/O	ST	
RP24	—	—	4	I/O	ST	
RP25	—	—	5	I/O	ST	
RPI4	11	8	33	I	ST	Remappable Peripheral (input).
RTCC	25	22	14	O	—	Real-Time Clock Alarm/Seconds Pulse Output.
SCL1	17	14	44	I/O	I^2C	I2C1 Synchronous Serial Clock Input/Output.
SCL2	7	4	24	I/O	I^2C	I2C2 Synchronous Serial Clock Input/Output.
SCLKI	12	9	34	I	—	Secondary Oscillator Digital Clock Input.
SDA1	18	15	1	I/O	I^2C	I2C1 Data Input/Output.
SDA2	6	3	23	I/O	I^2C	I2C2 Data Input/Output.
SOSCI	11	8	33	I	ANA	Secondary Oscillator/Timer1 Clock Input.
SOSCO	12	9	34	O	ANA	Secondary Oscillator/Timer1 Clock Output.

Legend: ST = Schmitt Trigger input TTL = TTL compatible input I = Input
ANA = Analog input O = Output P = Power
I^2C = ST with I^2C™ or SMBus levels

NOTES:

6.0 FLASH PROGRAM MEMORY

> **Note:** This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Program Memory"** (DS39715). The information in this data sheet supersedes the information in the FRM.

The PIC24FJ128GB204 family of devices contains internal Flash program memory for storing and executing application code. The program memory is readable, writable and erasable. The Flash memory can be programmed in four ways:

- In-Circuit Serial Programming™ (ICSP™)
- Run-Time Self-Programming (RTSP)
- JTAG
- Enhanced In-Circuit Serial Programming (Enhanced ICSP)

ICSP allows a PIC24FJ128GB204 family device to be serially programmed while in the end application circuit. This is simply done with two lines for the programming clock and programming data (named PGECx and PGEDx, respectively), and three other lines for power (VDD), ground (VSS) and Master Clear (MCLR). This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

RTSP is accomplished using `TBLRD` (Table Read) and `TBLWT` (Table Write) instructions. With RTSP, the user may write program memory data in blocks of 64 instructions (192 bytes) at a time and erase program memory in blocks of 512 instructions (1536 bytes) at a time.

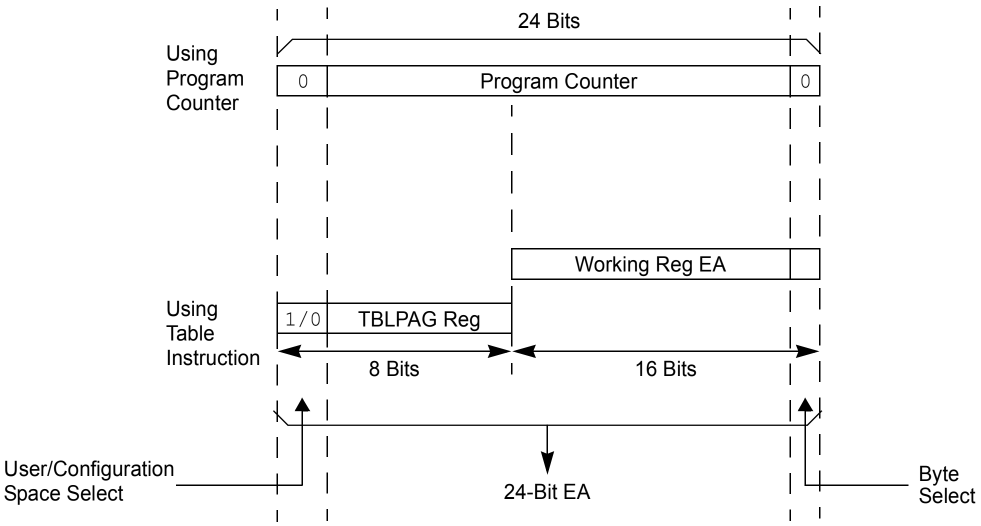
6.1 Table Instructions and Flash Programming

Regardless of the method used, all programming of Flash memory is done with the Table Read and Table Write instructions. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using the TBLPAG<7:0> bits and the Effective Address (EA) from a W register, specified in the table instruction, as shown in Figure 6-1.

The `TBLRDL` and the `TBLWTL` instructions are used to read or write to bits<15:0> of program memory. `TBLRDL` and `TBLWTL` can access program memory in both Word and Byte modes.

The `TBLRDH` and `TBLWTH` instructions are used to read or write to bits<23:16> of program memory. `TBLRDH` and `TBLWTH` can also access program memory in Word or Byte mode.

FIGURE 6-1: ADDRESSING FOR TABLE REGISTERS



10.6 Clock Frequency and Clock Switching

In Run and Idle modes, all PIC24FJ devices allow for a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSCx bits. The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.7 Doze Mode

Generally, changing clock speed and invoking one of the power-saving modes are the preferred strategies for reducing power consumption. There may be circumstances, however, where this is not practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed may introduce communication errors, while using a power-saving mode may stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default.

It is also possible to use Doze mode to selectively reduce power consumption in event driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption while the CPU Idles, waiting for something to invoke an interrupt routine. Enabling the automatic return to full-speed CPU operation on interrupts is enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

10.8 Selective Peripheral Module Control

Idle and Doze modes allow users to substantially reduce power consumption by slowing or stopping the CPU clock. Even so, peripheral modules still remain clocked, and thus, consume power. There may be cases where the application needs what these modes do not provide: the allocation of power resources to CPU processing, with minimal power consumption from the peripherals.

PIC24F devices address this requirement by allowing peripheral modules to be selectively disabled, reducing or eliminating their power consumption. This can be done with two control bits:

- The Peripheral Enable bit, generically named, "XXXEN", located in the module's main control SFR.
- The Peripheral Module Disable (PMD) bit, generically named, "XXXMD", located in one of the PMDx Control registers (XXXMD bits are in the PMD1, PMD2, PMD3, PMD4, PMD6, PMD7, PMD8 registers).

Both bits have similar functions in enabling or disabling its associated module. Setting the PMD bit for a module disables all clock sources to that module, reducing its power consumption to an absolute minimum. In this state, the control and status registers associated with the peripheral will also be disabled, so writes to those registers will have no effect and read values will be invalid. Many peripheral modules have a corresponding PMD bit.

In contrast, disabling a module by clearing its XXXEN bit disables its functionality, but leaves its registers available to be read and written to. Power consumption is reduced, but not by as much as the use of the PMD bits. Most peripheral modules have an enable bit; exceptions include capture, compare and RTCC.

To achieve more selective power savings, peripheral modules can also be selectively disabled when the device enters Idle mode. This is done through the control bit of the generic name format, "XXXSIDL". By default, all modules that can operate during Idle mode will do so. Using the disable on Idle feature disables the module while in Idle mode, allowing further reduction of power consumption during Idle mode, enhancing power savings for extremely critical power applications.

REGISTER 11-27: RPOR4: PERIPHERAL PIN SELECT OUTPUT REGISTER 4

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP9R5	RP9R4	RP9R3	RP9R2	RP9R1	RP9R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP8R5	RP8R4	RP8R3	RP8R2	RP8R1	RP8R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14	**Unimplemented:** Read as ‘0’
bit 13-8	**RP9R<5:0>:** RP9 Output Pin Mapping bits Peripheral Output Number n is assigned to pin, RP9 (see Table 11-4 for peripheral function numbers).
bit 7-6	**Unimplemented:** Read as ‘0’
bit 5-0	**RP8R<5:0>:** RP8 Output Pin Mapping bits Peripheral Output Number n is assigned to pin, RP8 (see Table 11-4 for peripheral function numbers).

REGISTER 11-28: RPOR5: PERIPHERAL PIN SELECT OUTPUT REGISTER 5

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP11R5	RP11R4	RP11R3	RP11R2	RP11R1	RP11R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP10R5	RP10R4	RP10R3	RP10R2	RP10R1	RP10R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14	**Unimplemented:** Read as ‘0’
bit 13-8	**RP11R<5:0>:** RP11 Output Pin Mapping bits Peripheral Output Number n is assigned to pin, RP11 (see Table 11-4 for peripheral function numbers).
bit 7-6	**Unimplemented:** Read as ‘0’
bit 5-0	**RP10R<5:0>:** RP10 Output Pin Mapping bits Peripheral Output Number n is assigned to pin, RP10 (see Table 11-4 for peripheral function numbers).

REGISTER 11-35: RPOR12: PERIPHERAL PIN SELECT OUTPUT REGISTER 12[1]

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP25R5	RP25R4	RP25R3	RP25R2	RP25R1	RP25R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP24R5	RP24R4	RP24R3	RP24R2	RP24R1	RP24R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP25R<5:0>:** RP25 Output Pin Mapping bits
Peripheral Output Number n is assigned to pin, RP25 (see Table 11-4 for peripheral function numbers).

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **RP24R<5:0>:** RP24 Output Pin Mapping bits
Peripheral Output Number n is assigned to pin, RP24 (see Table 11-4 for peripheral function numbers).

Note 1: These pins are not available in 28-pin devices.

14.0 INPUT CAPTURE WITH DEDICATED TIMERS

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Input Capture with Dedicated Timer"** (DS39722). The information in this data sheet supersedes the information in the FRM.

Devices in the PIC24FJ128GB204 family contain six independent input capture modules. Each of the modules offers a wide range of configuration and operating options for capturing external pulse events and generating interrupts.

Key features of the input capture module include:

- Hardware-configurable for 32-bit operation in all modes by cascading two adjacent modules
- Synchronous and Trigger modes of output compare operation, with up to 30 user-selectable sync/trigger sources available
- A 4-level FIFO buffer for capturing and holding timer values for several events
- Configurable interrupt generation
- Up to 6 clock sources available for each module, driving a separate, internal 16-bit counter

The module is controlled through two registers: ICxCON1 (Register 14-1) and ICxCON2 (Register 14-2). A general block diagram of the module is shown in Figure 14-1.

14.1 General Operating Modes

14.1.1 SYNCHRONOUS AND TRIGGER MODES

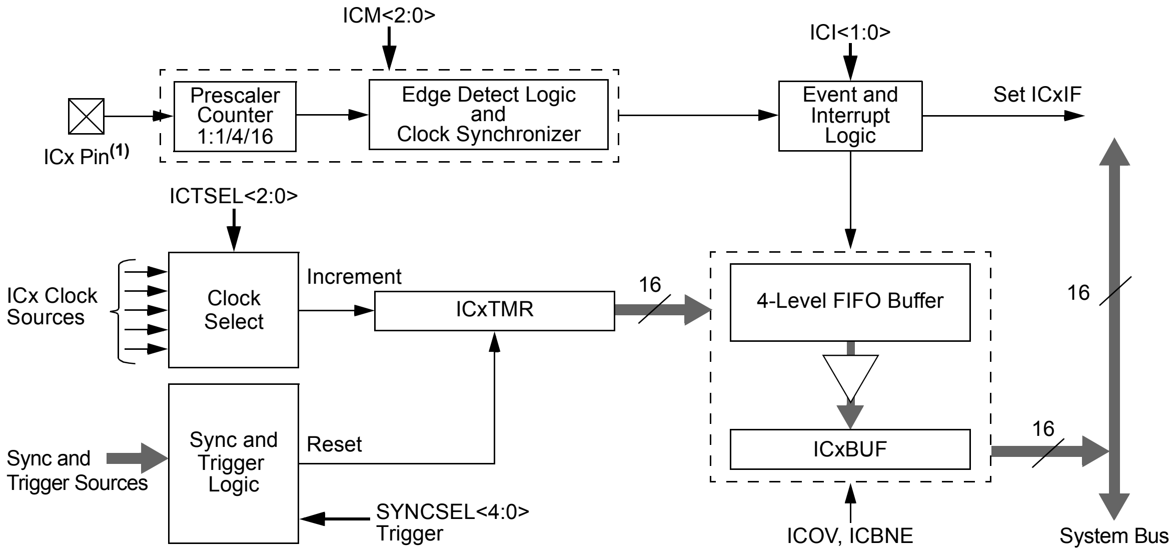
When the input capture module operates in a Free-Running mode, the internal 16-bit counter, ICxTMR, counts up continuously, wrapping around from FFFFh to 0000h on each overflow. Its period is synchronized to the selected external clock source. When a capture event occurs, the current 16-bit value of the internal counter is written to the FIFO buffer.

In Synchronous mode, the module begins capturing events on the ICx pin as soon as its selected clock source is enabled. Whenever an event occurs on the selected sync source, the internal counter is reset. In Trigger mode, the module waits for a sync event from another internal module to occur before allowing the internal counter to run.

Standard, free-running operation is selected by setting the SYNCSELx bits (ICxCON2<4:0>) to '00000' and clearing the ICTRIG bit (ICxCON2<7>). Synchronous and Trigger modes are selected any time the SYNCSELx bits are set to any value except '00000'. The ICTRIG bit selects either Synchronous or Trigger mode; setting the bit selects Trigger mode operation. In both modes, the SYNCSELx bits determine the sync/trigger source.

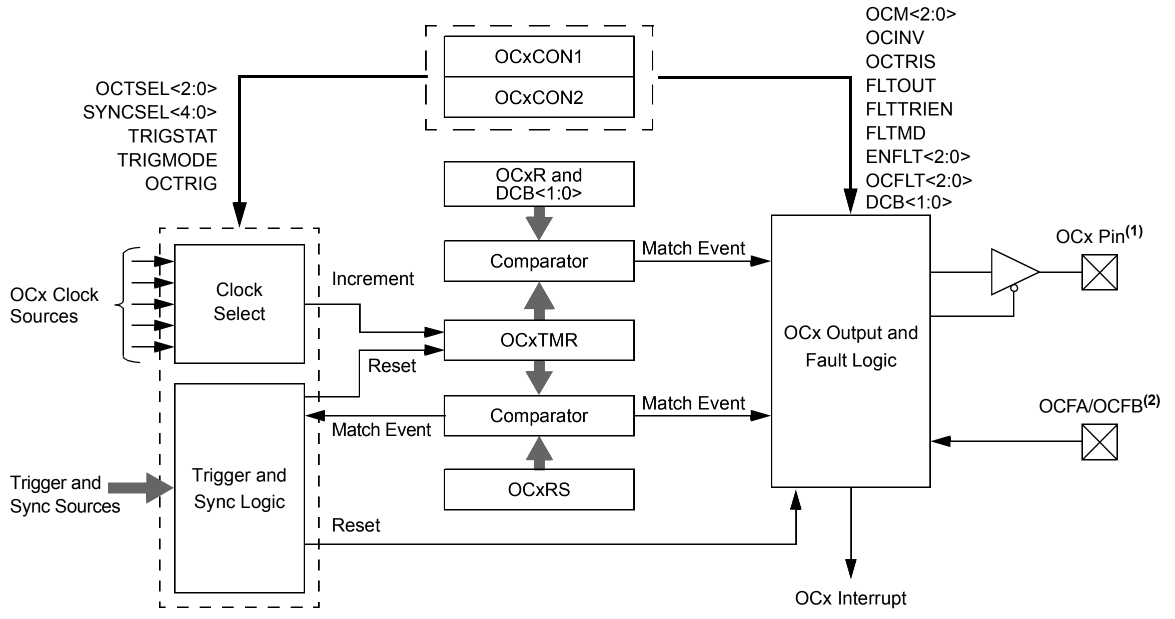
When the SYNCSELx bits are set to '00000' and ICTRIG is set, the module operates in Software Trigger mode. In this case, capture operations are started by manually setting the TRIGSTAT bit (ICxCON2<6>).

FIGURE 14-1: INPUT CAPTURE x BLOCK DIAGRAM



Note 1: The ICx inputs must be assigned to an available RPn/RPIn pin before use. See **Section 11.4 "Peripheral Pin Select (PPS)"** for more information.

FIGURE 15-1: OUTPUT COMPARE x BLOCK DIAGRAM (16-BIT MODE)



Note 1: The OCx outputs must be assigned to an available RPn pin before use. For more information, see **Section 11.4 "Peripheral Pin Select (PPS)"**.

2: The OCFA/OCFB Fault inputs must be assigned to an available RPn/RPIn pin before use. For more information, see **Section 11.4 "Peripheral Pin Select (PPS)"**.

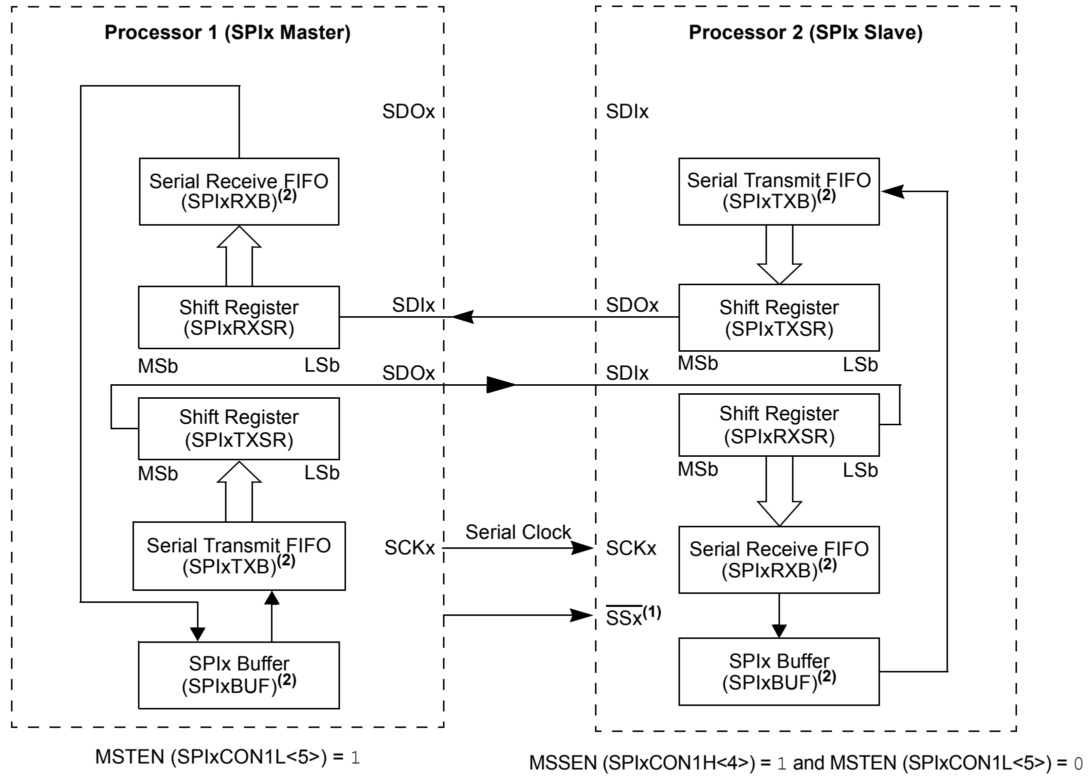
15.2 Compare Operations

In Compare mode (Figure 15-1), the output compare module can be configured for single-shot or continuous pulse generation. It can also repeatedly toggle an output pin on each timer event.

To set up the module for compare operations:

1. Configure the OCx output for one of the available Peripheral Pin Select pins.
2. Calculate the required values for the OCxR and (for Double Compare modes) OCxRS Duty Cycle registers:
   a) Determine the instruction clock cycle time. Take into account the frequency of the external clock to the timer source (if one is used) and the timer prescaler settings.
   b) Calculate the time to the rising edge of the output pulse relative to the timer start value (0000h).
   c) Calculate the time to the falling edge of the pulse based on the desired pulse width and the time to the rising edge of the pulse.
3. Write the rising edge value to OCxR and the falling edge value to OCxRS.
4. Set the Timer Period register, PRy, to a value equal to or greater than the value in OCxRS.
5. Set the OCM<2:0> bits for the appropriate compare operation ('0xx').
6. For Trigger mode operations, set OCTRIG to enable Trigger mode. Set or clear TRIGMODE to configure trigger operation and TRIGSTAT to select a hardware or software trigger. For Synchronous mode, clear OCTRIG.
7. Set the SYNCSEL<4:0> bits to configure the trigger or synchronization source. If free-running timer operation is required, set the SYNCSELx bits to '00000' (no sync/trigger source).
8. Select the time base source with the OCTSEL<2:0> bits. If necessary, set the TON bit for the selected timer, which enables the compare time base to count. Synchronous mode operation starts as soon as the time base is enabled; Trigger mode operation starts after a trigger source event occurs.

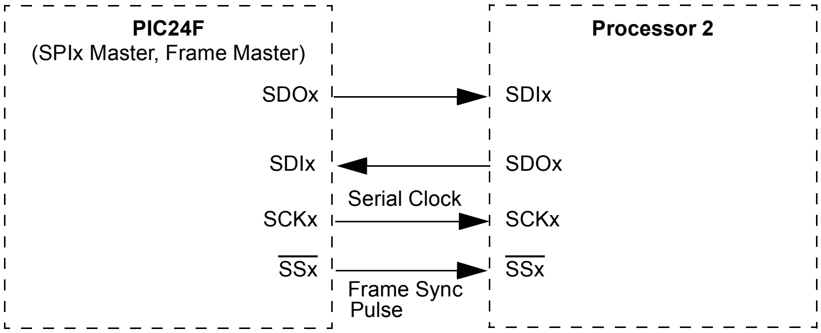
FIGURE 16-4: SPIx MASTER/SLAVE CONNECTION (ENHANCED BUFFER MODES)


Processor 1 (SPIx Master)
Processor 2 (SPIx Slave)
SDOx
SDIx
Serial Receive FIFO (SPIxRXB)(2)
Serial Transmit FIFO (SPIxTXB)(2)
Shift Register (SPIxRXSR)
SDIx
SDOx
Shift Register (SPIxTXSR)
MSb
LSb
SDOx
SDIx
MSb
LSb
Shift Register (SPIxTXSR)
Shift Register (SPIxRXSR)
MSb
LSb
MSb
LSb
Serial Transmit FIFO (SPIxTXB)(2)
SCKx
Serial Clock
SCKx
Serial Receive FIFO (SPIxRXB)(2)
SSx(1)
SPIx Buffer (SPIxBUF)(2)
SPIx Buffer (SPIxBUF)(2)
MSTEN (SPIxCON1L<5>) = 1
MSSEN (SPIxCON1H<4>) = 1 and MSTEN (SPIxCON1L<5>) = 0

Note 1: Using the SSx pin in Slave mode of operation is optional.

2: User must write transmit data to read the received data from SPIxBUF. The SPIxTXB and SPIxRXB registers are memory-mapped to SPIxBUF.

FIGURE 16-5: SPIx MASTER, FRAME MASTER CONNECTION DIAGRAM



17.2 Setting Baud Rate When Operating as a Bus Master

To compute the Baud Rate Generator reload value, use Equation 17-1.

EQUATION 17-1: COMPUTING BAUD RATE RELOAD VALUE[(1)]

$$I2CxBRG = \left(\left(\frac{1}{F_{SCL}} - PGDx\right) \times \frac{F_{CY}}{2}\right) - 2$$

Note 1: Based on $F_{CY} = F_{OSC}/2$; Doze mode and PLL are disabled.

17.3 Slave Address Masking

The I2CxMSK register (Register 17-4) designates address bit positions as "don't care" for both 7-Bit and 10-Bit Addressing modes. Setting a particular bit location (= 1) in the I2CxMSK register causes the slave module to respond, whether the corresponding address bit value is a '0' or a '1'. For example, when I2CxMSK is set to '0010000000', the slave module will detect both addresses, '0000000000' and '0010000000'.

To enable address masking, the Intelligent Peripheral Management Interface (IPMI) must be disabled by clearing the STRICT bit (I2CxCONL<11>).

Note: As a result of changes in the I^{2}C™ protocol, the addresses in Table 17-1 are reserved and will not be Acknowledged in Slave mode. This includes any address mask settings that include any of these addresses.

TABLE 17-1: I^{2}C™ RESERVED ADDRESSES[(1)]

Slave Address	R/$\overline{W}$ Bit	Description
0000 000	0	General Call Address[(2)]
0000 000	1	Start Byte
0000 001	x	Cbus Address
0000 01x	x	Reserved
0000 1xx	x	HS Mode Master Code
1111 0xx	x	10-Bit Slave Upper Byte[(3)]
1111 1xx	x	Reserved

Note 1: The address bits listed here will never cause an address match independent of address mask settings.

2: The address will be Acknowledged only if GCEN = 1.

3: A match on this address can only occur on the upper byte in 10-Bit Addressing mode.

NOTES:

REGISTER 22-3: ALCFGRPT: ALARM CONFIGURATION REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ALRMEN	CHIME	AMASK3	AMASK2	AMASK1	AMASK0	ALRMPTR1	ALRMPTR0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ARPT7	ARPT6	ARPT5	ARPT4	ARPT3	ARPT2	ARPT1	ARPT0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ALRMEN:** Alarm Enable bit

1 = Alarm is enabled (cleared automatically after an alarm event whenever ARPT<7:0> = 00h and CHIME = 0)
0 = Alarm is disabled

bit 14 **CHIME:** Chime Enable bit

1 = Chime is enabled; ARPT<7:0> bits are allowed to roll over from 00h to FFh
0 = Chime is disabled; ARPT<7:0> bits stop once they reach 00h

bit 13-10 **AMASK<3:0>:** Alarm Mask Configuration bits

0000 = Every half second
0001 = Every second
0010 = Every 10 seconds
0011 = Every minute
0100 = Every 10 minutes
0101 = Every hour
0110 = Once a day
0111 = Once a week
1000 = Once a month
1001 = Once a year (except when configured for February 29th, once every 4 years)
101x = Reserved – do not use
11xx = Reserved – do not use

bit 9-8 **ALRMPTR<1:0>:** Alarm Value Register Window Pointer bits

Points to the corresponding Alarm Value registers when reading the ALRMVALH and ALRMVALL registers. The ALRMPTR<1:0> value decrements on every read or write of ALRMVALH until it reaches ‘00’.

ALRMVAL<15:8>:
00 = ALRMMIN
01 = ALRMWD
10 = ALRMMNTH
11 = PWCSTAB

ALRMVAL<7:0>:
00 = ALRMSEC
01 = ALRMHR
10 = ALRMDAY
11 = PWCSAMP

bit 7-0 **ARPT<7:0>:** Alarm Repeat Counter Value bits

11111111 = Alarm will repeat 255 more times
•
•
•
00000000 = Alarm will not repeat

The counter decrements on any alarm event; it is prevented from rolling over from 00h to FFh unless CHIME = 1.

NOTES:

24.1.3 DATA SHIFT DIRECTION

The LENDIAN bit (CRCCON1<3>) is used to control the shift direction. By default, the CRC will shift data through the engine, MSb first. Setting LENDIAN (= 1) causes the CRC to shift data, LSb first. This setting allows better integration with various communication schemes and removes the overhead of reversing the bit order in software. Note that this only changes the direction the data is shifted into the engine. The result of the CRC calculation will still be a normal CRC result, not a reverse CRC result.

24.1.4 INTERRUPT OPERATION

The module generates an interrupt that is configurable by the user for either of two conditions.

If CRCISEL is '0', an interrupt is generated when the VWORD<4:0> bits make a transition from a value of '1' to '0'. If CRCISEL is '1', an interrupt will be generated after the CRC operation finishes and the module sets the CRCGO bit to '0'. Manually setting CRCGO to '0' will not generate an interrupt. Note that when an interrupt occurs, the CRC calculation would not yet be complete. The module will still need (PLEN + 1)/2 clock cycles, after the interrupt is generated, until the CRC calculation is finished.

24.1.5 TYPICAL OPERATION

To use the module for a typical CRC calculation:

1. Set the CRCEN bit to enable the module.
2. Configure the module for desired operation:
   a) Program the desired polynomial using the CRCXORL and CRCXORH registers, and the PLEN<4:0> bits.
   b) Configure the data width and shift direction using the DWIDTHx and LENDIAN bits.
   c) Select the desired Interrupt mode using the CRCISEL bit.
3. Preload the FIFO by writing to the CRCDATL and CRCDATH registers until the CRCFUL bit is set or no data is left.
4. Clear old results by writing 00h to CRCWDATL and CRCWDATH. The CRCWDAT registers can also be left unchanged to resume a previously halted calculation.
5. Set the CRCGO bit to start calculation.
6. Write remaining data into the FIFO as space becomes available.
7. When the calculation completes, CRCGO is automatically cleared. An interrupt will be generated if CRCISEL = 1.
8. Read CRCWDATL and CRCWDATH for the result of the calculation.

There are eight registers used to control programmable CRC operation:

- CRCCON1
- CRCCON2
- CRCXORL
- CRCXORH
- CRCDATL
- CRCDATH
- CRCWDATL
- CRCWDATH

The CRCCON1 and CRCCON2 registers (Register 24-1 and Register 24-2) control the operation of the module and configure the various settings.

The CRCXORL/H registers (Register 24-3 and Register 24-4) select the polynomial terms to be used in the CRC equation. The CRCDAT and CRCWDAT registers are each register pairs that serve as buffers for the double-word input data and CRC processed output, respectively.

REGISTER 25-1: AD1CON1: ADC1 CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADON	—	ADSIDL	DMABM[1]	DMAEN	MODE12	FORM1	FORM0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0, HSC	R/C-0, HSC
SSRC3	SSRC2	SSRC1	SSRC0	—	ASAM	SAMP	DONE
bit 7							bit 0

Legend:	C = Clearable bit	U = Unimplemented bit, read as ‘0’	
R = Readable bit	W = Writable bit	HSC = Hardware Settable/Clearable bit	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ADON:** ADC1 Operating Mode bit

1 = A/D Converter module is operating
0 = A/D Converter is off

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **ADSIDL:** ADC1 Stop in Idle Mode bit

1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **DMABM:** Extended DMA Buffer Mode Select bit[1]

1 = Extended Buffer mode: Buffer address is defined by the DMADSTn register
0 = PIA mode: Buffer addresses are defined by the DMA Controller and AD1CON4<2:0>

bit 11 **DMAEN:** Extended DMA/Buffer Enable bit

1 = Extended DMA and buffer features are enabled
0 = Extended features are disabled

bit 10 **MODE12:** ADC1 12-Bit Operation Mode bit

1 = 12-bit A/D operation
0 = 10-bit A/D operation

bit 9-8 **FORM<1:0>:** Data Output Format bits (see the following formats)

11 = Fractional result, signed, left justified
10 = Absolute fractional result, unsigned, left justified
01 = Decimal result, signed, right justified
00 = Absolute decimal result, unsigned, right justified

bit 7-4 **SSRC<3:0>:** Sample Clock Source Select bits

1xxx = Unimplemented, do not use
0111 = Internal counter ends sampling and starts conversion (auto-convert); do not use in Auto-Scan mode
0110 = Unimplemented
0101 = TMR1
0100 = CTMU
0011 = TMR5
0010 = TMR3
0001 = INT0
0000 = The SAMP bit must be cleared by software to start conversion

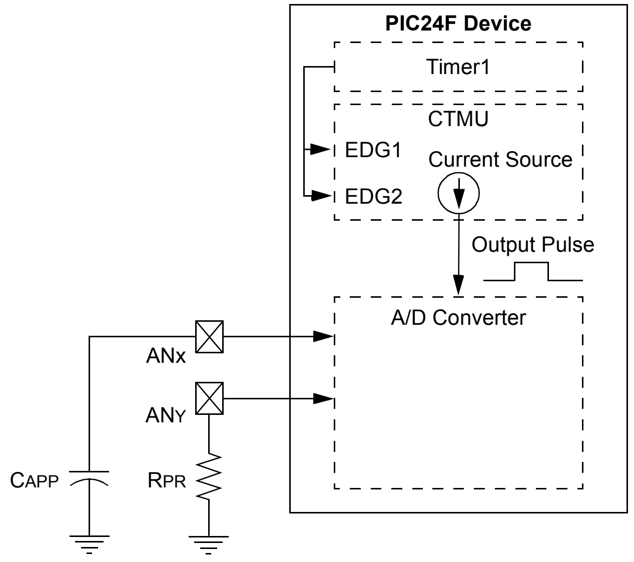
bit 3 **Unimplemented:** Read as ‘0’

bit 2 **ASAM:** ADC1 Sample Auto-Start bit

1 = Sampling begins immediately after last conversion; SAMP bit is auto-set
0 = Sampling begins when SAMP bit is manually set

Note 1: This bit is only available when Extended DMA/Buffer features are available (DMAEN = 1).

FIGURE 28-1: TYPICAL CONNECTIONS AND INTERNAL CONFIGURATION FOR CAPACITANCE MEASUREMENT



31.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

31.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

31.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

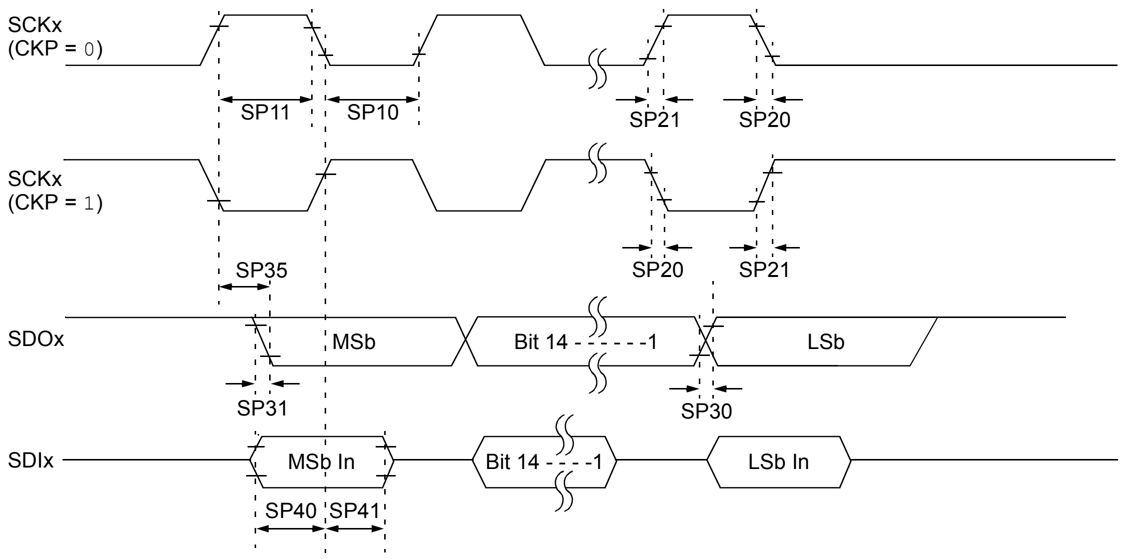
- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

31.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

FIGURE 33-9: SPIx MODULE MASTER MODE (CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 33-2 for load conditions.

TABLE 33-32: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min**	**Typ[2]**	**Max**	**Units**	**Conditions**
SP10	TscL	SCKx Output Low Time	TCY/2	—	—	ns	(Note 3)
SP11	TscH	SCKx Output High Time	TCY/2	—	—	ns	(Note 3)
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid After SCKx Edge	—	6	20	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	23	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	

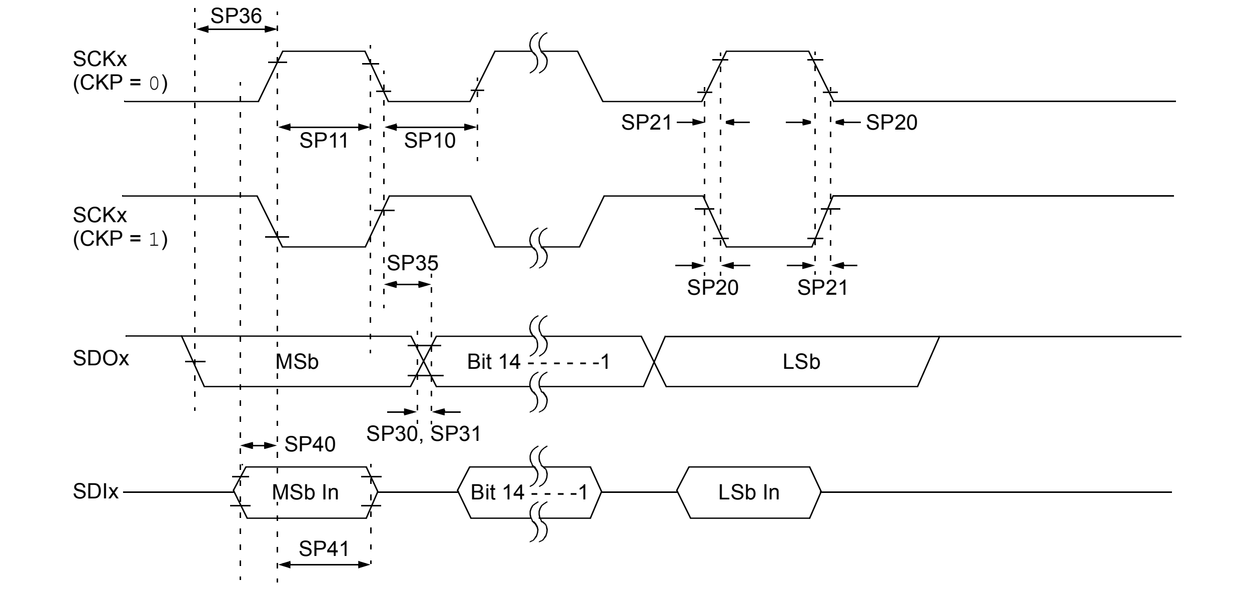
Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 100 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 33-10: SPIx MODULE MASTER MODE (CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 33-2 for load conditions.

TABLE 33-33: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min**	**Typ[2]**	**Max**	**Units**	**Conditions**
SP10	TscL	SCKx Output Low Time[3]	TCY/2	—	—	ns	
SP11	TscH	SCKx Output High Time[3]	TCY/2	—	—	ns	
SP20	TscF	SCKx Output Fall Time[4]	—	—	—	ns	See Parameter DO32
SP21	TscR	SCKx Output Rise Time[4]	—	—	—	ns	See Parameter DO31
SP30	TdoF	SDOx Data Output Fall Time[4]	—	—	—	ns	See Parameter DO32
SP31	TdoR	SDOx Data Output Rise Time[4]	—	—	—	ns	See Parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid After SCKx Edge	—	6	20	ns	
SP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	23	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	

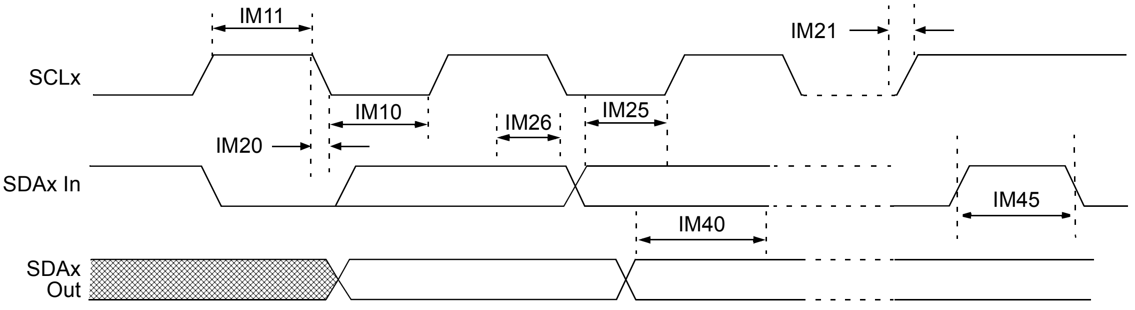
Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 100 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 33-14: I^{2}C™ BUS DATA TIMING CHARACTERISTICS (MASTER MODE)



Note: Refer to Figure 33-2 for load conditions.

TABLE 33-37: I^{2}C™ BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				**Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic**		**Min[1]**	**Max**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TCY (BRG + 1)	—	μs	
			400 kHz mode	TCY (BRG + 1)	—	μs	
			1 MHz mode[2]	TCY (BRG + 1)	—	μs	
IM11	THI:SCL	Clock High Time	100 kHz mode	TCY (BRG + 1)	—	μs	
			400 kHz mode	TCY (BRG + 1)	—	μs	
			1 MHz mode[2]	TCY (BRG + 1)	—	μs	
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode[2]	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode[2]	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	
			400 kHz mode	100	—	ns	
			1 MHz mode[2]	40	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
			1 MHz mode[2]	0.2	—	ns	
IM40	TAA:SCL	Output Valid From Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
			1 MHz mode[2]	—	400	ns	
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
			1 MHz mode[2]	0.5	—	μs	
IM50	CB	Bus Capacitive Loading		—	400	pF	

Note 1: BRG is the value of the I^{2}C Baud Rate Generator. Refer to **Section 17.2 “Setting Baud Rate When Operating as a Bus Master”** for details.

2: Maximum Pin Capacitance = 10 pF for all I^{2}C pins (for 1 MHz mode only).